

SRAM-TYPE MEMORY CELL

FIELD OF THE INVENTION

The present invention relates to an SRAM-type memory cell formed on a semiconductor on insulator substrate and comprising six transistors.

5 BACKGROUND OF THE INVENTION

SRAM ("Static Random Access Memory") type memory cells are static ram memories, that is to say memories that do not require periodic refreshing.

Such memory cells are constructed from a set of transistors.

10 A general concern in this field is how to reduce the size of the cells and how to reduce the leakage currents.

When an SRAM cell is fabricated on a bulk substrate, the size reduction results in a greater variability, which means that the dimensions of the transistors must not be reduced too much, and the read and write components must be separated in order to find an operating point.

15 This may entail increasing the number of transistors (thus increasing from 6 to 8, or even 10 transistors), with an attendant penalty in terms of surface area.

Moreover, on a "bulk" type substrate, the transistors have different dimensions, depending on their function within the cell (transfer, charge, conduction).

20 Authors have proposed using FD-SOI type transistors (an acronym standing for "Fully-Depleted SOI", which describes a fully depleted structure produced on a silicon on insulator substrate) comprising a back control gate.

Reference in this respect can be made to the publications by Yamaoka *et al.* ("SRAM Circuit With Expanded Operating Margin and Reduced Stand-By Leakage Current Using Thin-BOX FD-SOI Transistors", IEEE Journal of Solid-State Circuits, Vol. 41, No 11, Nov. 25 2006) and by Tsuchiya *et al.* ("Silicon on Thin BOX: A New Paradigm of the CMOSFET for Low-Power and High-Performance Application Featuring Wide-Range Back-Bias Control", IEEE 2004).

A conventional SRAM cell typically comprises six transistors, namely:

- 30 - two access or transfer transistors: these are generally N channel field-effect transistors (NFETs),
- two charge transistors and two conduction transistors, linked in pairs so as to form two back-coupled inverters: the charge transistors are, in theory, P channel FET transistors (PFETs) and the conduction transistors are NFET transistors.

35 In the abovementioned publications, the back control gate, which is formed under the insulator, is used to control the operating conditions of the transistors more accurately.

The back control gate is a doped region formed under each transistor, each group of transistors and the underlying gate corresponding to an N+ or P+ type island being insulated from the others by so-called "STI" ("Shallow Trench Isolation")

Thus, in an SRAM cell, the PFET transistors belong to one and the same island, while
5 the NFET transistors are grouped in pairs (access transistors and conduction transistors respectively) in islands separated by the P region.

In practice, these two N regions are linked together at the periphery and to the other regions of the same type for the other columns. The same applies for the P region.

For N channel transistors, the region forming the back control gate is of P+ type, and is
10 separated from the P type base substrate by a layer of N conductivity.

For the P channel transistors, the region forming the back control gate is of N+ type.

The article by Yamaoka *et al.* discloses a back control gate common to the two charge transistors, which are of P type, and a back control gate common to the access transistors and to the conduction transistors which are of N type.

15 In the article by Tsuchiya *et al.*, the access transistors have a back control gate linked to ground and each pair formed by a charge transistor and a conduction transistor has a common back control gate.

However, in these devices, the back control gate simply comprises a well which is limited by the isolating trench.

20 Moreover, the choice of working in columns of wells does not favour the facilitation of the operating modes.

For example, the article by Yamaoka *et al.* describes N access transistors and N conduction transistors having the same back control gate such that their ratio remains constant regardless of the operating mode, thereby limiting the margin for improvement for
25 the various functional modes.

Research is therefore focused on obviating the drawbacks of the existing devices and further reducing the dimensions of the SRAM-type memory cells, so as to conform roughly to Moore's law, while improving the performance levels of such cells.

30 BRIEF DESCRIPTION OF THE INVENTION

According to a first aspect of the invention, there is provided an SRAM-type memory cell comprising:

- a semiconductor on insulator substrate comprising a thin film of semiconductor material separated from a base substrate by an insulating layer;
- six transistors, comprising two access transistors, two conduction transistors and two
35 charge transistors arranged so as to form with said conduction transistors two back-

coupled inverters, each of the transistors comprising a drain region and a source region arranged in the thin film, a channel extending between the source region and the drain region and a front gate situated above the channel,

said memory cell being characterized in that each of the transistors has a back control gate formed in the base substrate below the channel and able to be biased to modulate the threshold voltage of the transistor, a first back gate line connecting the back control gates of the access transistors to a first potential and a second back gate line connecting the back control gates of the conduction transistors and charge transistors to a second potential, the first and second potentials being modulated according to the type of cell control operation.

According to embodiments of the invention:

- the access transistors and conduction transistors are NFET transistors, the charge transistors are PFET transistors; the back control gate of the access transistors is of N+ conductivity and the back control gate of the conduction transistors and charge transistors is of N+ conductivity;
- the back control gate of the conduction transistors and charge transistors is arranged in the base substrate below the channel in a well of conductivity opposite to the conductivity of the back control gate;
- the memory cell is fully depleted.

According to a second aspect of the invention, there is provided a memory array comprising a plurality of memory cells as described hereinabove, in which the channel of each of the transistors has a minimal physical width but has an apparent width that can be modulated by the application of a potential to the back control gate of said transistor.

According to a third aspect of the invention, there is provided a method of fabricating an SRAM-type memory cell as described above, comprising the steps of:

- providing said semiconductor on insulator substrate comprising said thin film of semiconductor material separated from the base substrate by said insulating layer,
- forming back control gates in the base substrate by implantation.

According to a fourth aspect of the invention, there is provided a method of controlling a memory cell as described above, characterized in that a so-called "high" positive voltage and a so-called "low" positive or zero voltage less than the high voltage is defined to bias the back control gates of the transistors, and in that, according to the type of cell control operation, a high voltage or a low voltage is dynamically applied to the back control gate of the transistors.

According to embodiments of the invention:

- it comprises, for a standby operation, the application of a low voltage to the back control gate of the access transistors and to the back control gate of the conduction transistors and charge transistors;
- it comprises, for a read operation, the application of a low voltage to the back control gate of the access transistors and a high voltage to the back control gate of the conduction transistors and charge transistors;
- it comprises, for a write operation, the application of a high voltage to the back control gate of the access transistors and a low voltage to the back control gate of the conduction transistors and charge transistors.

BRIEF DESCRIPTION OF THE DRAWINGS

Other features and advantages of the invention will emerge from the following detailed description, with reference to the appended drawings in which:

- Figure 1 is a circuit diagram of an SRAM cell according to the invention,
- Figure 2 illustrates the topology of the SRAM cell,
- Figure 3 is a view in cross section on A-A of the cell illustrated in Figure 2;
- Figure 4 is a view in cross-section on B-B of the cell illustrated in Figure 2;
- Figure 5 illustrates the topology of an SRAM array comprising a plurality of cells according to the invention;
- Figure 6 illustrates the modalities controlling the threshold voltage of a transistor by virtue of the back control gate.

DETAILED DESCRIPTION OF THE INVENTION

Structure of the SRAM cell

Figure 1 shows the circuit diagram corresponding to an SRAM-type memory cell according to the invention.

The memory cell comprises six transistors T1 to T6.

Two of these transistors are access transistors T1 and T4.

The transistors T1 and T4 are produced on a semiconductor on insulator substrate and each of the transistors has a front gate G and a back control gate BG1 that can be controlled to modify the behaviour of the transistor.

Preferably a back gate line is used to collectively connect the back control gate BG1 of the two access transistors T1, T4 to one and the same potential, which makes it possible to provide easy and inexpensive control, but it is also possible for each of the back gates to be individually connected to a potential.

The front gate G of each of the access transistors T1 and T4 is linked to a word line WL.

Moreover, a drain electrode of each of the access transistors T1 and T4 is linked to a bit line, respectively BL1 and BL2, the bit line BL2 complementing the bit line BL1.

The memory cell further comprises two inverters, each comprising a charge transistor
 5 T3, T6 and a conduction transistor T2, T5 in series between a power supply voltage VDD and ground GND. Each inverter has an input consisting of the front gates common to the series transistors, and an output consisting of the sources common to the series transistors.

These inverters are back-coupled in a manner conventionally known per se, the input of one inverter being linked to the output of the other, and vice versa.

10 It will also be noted that, like the access transistors T1 and T4, the transistors T2, T3, T5 and T6 have, in addition to a front gate G, a back control gate BG2.

Preferably, a back gate line is used to collectively connect the back control gates BG2 of the transistors T2, T3, T5 and T6 to one and the same potential, which makes it possible to provide easy and inexpensive control, but it is also possible for each of the back gates to be
 15 connected separately to a potential.

Preferably, the back control gates BG1 and BG2 are independent from and not connected with the sources and drains of transistors T1-T6. The voltages applied to the control back gates BG1 and BG2 are independent from the power supply voltage VDD and ground GND, and can be of any one of a continuous range of values, for example VDD/2 or
 20 VDD/3.

The access transistors T1, T4 are used to control access to the back-coupled inverters during the memory cell's read and write operations.

The source electrode of each access transistor T1, T4 is thus connected to the output of one of the inverters and to the input of the other inverter.

25 Figure 2 illustrates the topology of the corresponding memory cell.

Figure 3 is a cross section on A-A of the cell illustrated in Figure 2.

We will focus first on the access transistor T1 (the explanations given being valid for the second access transistor T4).

The semiconductor on insulator substrate comprises a thin film 1 of semiconductor
 30 material separated from a base substrate 2 by an insulating layer.

The semiconductor on insulator substrate is, for example, a silicon on insulator SOI substrate.

According to a preferred embodiment, the insulating layer is a Buried Oxide BOX layer.

The insulating layer is, for example, made of SiO₂.

The transistor T1 is an NFET transistor which has a source region S, a drain region D and a floating channel C extending between the source region and the drain region.

The drain D and source S regions are preferentially in contact with the insulating BOX layer so that the transistor is fully depleted. The substrate is then qualified as "FD SOI".

5 It is also possible for the transistor to be partially depleted, but this technology is less advantageous because the thicknesses of the thin film of semiconductor material and of the insulating layer are greater, so that the effect of the back control gate becomes very weak (just a few %); furthermore, in this case, the channel must be doped, which corresponds to a situation comparable to that of the bulk substrate in terms of variability.

10 The front gate G extends in a manner conventionally known per se on the surface of the substrate, above the channel C and is separated therefrom by a dielectric layer 3.

In the context of the invention, the back control gate BG1 of the transistor T1 is arranged in the base substrate 2 under the insulating BOX layer facing the channel C of said transistor.

15 As can also be seen in Figure 3, the transistor T2 is an NFET transistor (like the transistor T5) which has a source region S, a drain region D and a floating channel C extending between the source region and the drain region.

The drain D and source S regions are preferentially in contact with the insulating BOX layer so that the transistor is fully depleted.

20 The front gate G extends in a manner conventionally known per se on the surface of the substrate, above the channel C, and is separated therefrom by a dielectric layer 3.

In the context of the invention, the back control gate BG2 of the transistor T2 is arranged in the base substrate 2 under the insulating BOX layer facing the channel C of said transistor.

25 Referring to Figure 4, the transistor T3 is a PFET transistor (like the transistor T6) which has a source region S, a drain region D and a floating channel C extending between the source region and the drain region.

The drain D and source S regions are preferentially in contact with the insulating BOX layer so that the transistor is fully depleted.

30 Alternatively, as explained above, the transistors T2, T3, T5 and T6 can also be partially depleted.

The front gate G extends in a manner conventionally known per se on the surface of the substrate, above the channel C, and is separated therefrom by a dielectric layer 3.

In the context of the invention, the back control gate BG2 of the transistor T3 is arranged in the base substrate 2 under the insulating BOX layer facing the channel C of said transistor.

As a purely illustrative example, the thickness of the thin film 1 of the semiconductor on insulator substrate is between 1.5 nm and 50 nm, the thickness of the insulating BOX layer is between 1.5 and 50 nm.

If the back control gate is not to have any differential working function, a conductivity of the latter will be chosen to be of the same type as that of the FET transistor (in other words, an N type conductivity for an N channel transistor, a P type conductivity for a P channel transistor).

To minimize the leakage currents in standby mode, the ideal situation would be to have a top doped region with a dopant concentration of around 10^{18} cm^{-3} or greater and of the opposite type to that of each of the transistors, and under all the transistors.

However, this would require the formation of three different back control gates under the memory cell, which would have the immediate effect of increasing the surface area of the cell by around 50% or more, because it would then be necessary to reconnect the back control gates individually in each cell.

Since the desired aim is to minimize the dimension of the transistors in order to minimize the surface area of the SRAM cell, the most appropriate trade-off has therefore been defined.

Thus, the access transistors T1 and T4 are NFET transistors with a back control gate BG1 of N+ type.

The conduction transistors T2 and T5 are NFET transistors with a back control gate BG2 of N+ type.

The charge transistors T3 and T6 are PFET transistors with a back control gate BG2 of N+ type.

As shown in Figures 3 and 4, the back control gates BG1 and BG2 are insulated from the base substrate 6 by a well denoted 4 and 5 respectively with a bias opposite to the bias of the P- substrate, the substrate 2 comprising the regions 4, 5 and 6.

The well 4 is of N- type for an N+ back control gate BG1; the well 5 is of P- type for an N+ back control gate BG2.

The voltage of the well 4, 5 is chosen so that the parasitic diode created by the electrical node between the back control gate and the well is always reversed, the diode isolating the back control gate from the well and from the back control gate BG2.

The invention also relates to a memory array comprising a plurality of SRAM cells as described above.

Such an array is illustrated in Figure 5.

The array is organized in rows and columns.

5 By convention, the row is represented by the direction of the word line WL (in the case of this invention, it is also the direction of the back control gate BG2 of the transistors T2, T3, T5 and T6), which is horizontal in Figure 5 while the column is in the direction of the bit lines (consisting of metal), which are vertical (not shown in Figure 5).

The array comprises as many rows and columns as the application requires.

10 In the case of this invention, the memory cells have the particular feature of having back control gates BG1 and BG2.

The back control gate BG2 of the inverters is decoded on the one hand by the addressing (as for the word line WL) and on the other hand by the operating mode (read or write).

15 The back control gate BG1 "modulates" the access transistors in the islands I (see figure 5).

The islands I are linked together under the cell by the well 4.

The N+ conductivity of the back control gate BG1 is necessary to avoid the formation of a diode and thus allow biasing directly under the transistor.

20 Method of fabricating the SRAM cell

The SRAM cell is fabricated by the usual method of aligning masks relative to one another.

An appropriate method is described, for example, in chapter 2 of the work entitled "CMOS Digital Integrated Circuit Design: Analysis and Design" by S.M. Kang and Y. Leblebici, McGraw-Hill Publishing Co., New York, NY, 2003.

The levels situated under the insulating BOX layer are all formed by implantation.

Controlling the properties of the transistors of the SRAM cell

30 In the context of the invention, the back control gates BG1 and BG2 are used dynamically: the voltage applied to them is effectively modulated according to the type of cell control operation (standby, read, write).

By biasing the back control gate of each transistor positively or negatively (typically by +/- 0.3 V), the properties of the transistor can be modified individually.

In particular, the threshold voltage of the transistor can be offset.

35 As it happens, modifying the threshold voltage is equivalent to modifying the physical width of the channel.

Thus, in the context of the invention, the physical width of the channel is defined once and for all and for all the transistors, but it is possible to modify, individually for each transistor, the apparent (effective) width of its channel via the control of the back control gate.

Since the voltage applied to the back control gate can be modified, the invention thus offers the advantage of a dynamic modification of the apparent width of the channel.

The variation of the threshold voltage of a transistor via the back control gate can be expressed by the formula:

$$V_{th} = V_{t0} - \alpha \cdot V_{BG},$$

in which V_{th} represents the threshold voltage of the transistor, V_{BG} the voltage applied to the back gate, V_{t0} the nominal threshold voltage (which can be offset by the working function depending on whether an N or P type back control gate is used), and α a coefficient linked to the geometry of the transistor.

The coefficient α can in particular be modelled according to the relation:

$$\alpha = \frac{3 \cdot t_{ox1}}{t_{Si} + 3 \cdot t_{ox2}},$$

in which t_{ox1} designates the thickness of the gate dielectric layer separating the front gate from the channel, t_{ox2} designates the thickness of the insulating layer separating the back control gate from the channel and t_{Si} designates the thickness of the thin film.

It will therefore be understood that the type of doping of the back control gate of a transistor may or may not offset the nominal threshold voltage, and that the biasing of the back control gate makes it possible to adjust the threshold voltage.

It is thus possible to benefit from an increase in the conduction current I_{ON} in an active state of the transistor (by reducing the threshold voltage), and a reduction of the leakage current I_{OFF} in an inactive state of the transistor (by increasing the threshold voltage).

The threshold voltages can then be reduced by applying to the back control gate a voltage that is positive for an N transistor and less than V_{DD} for a P transistor.

The invention is not, moreover, limited to the use of a zero or positive back control gate voltage, but also extends to the use of a zero or negative back control gate voltage.

The coefficient α decreases rapidly when the silicon and BOX thicknesses are too great.

For example, consider a V_{t0} of 0.35 V, to which is added a working function of 0.15 V: a threshold voltage V_{th} of 0.5 V is obtained.

If an operating mode requires the threshold voltage V_{th} to reach 0.2 V in order to operate, α must equal 0.3 (for a power supply voltage $V_{DD} = 1$ V).

If the thickness ratios do not permit this, the working function must be lowered (by refining the process) so as to achieve the voltage of 0.2 V required by the operating mode.

It is obviously necessary to compensate with a negative back control gate voltage in the other modes in order to “find” the 0.5 V required by these modes.

Figure 6 illustrates the control of the threshold voltage of a transistor produced on an SOI (or, generically, semiconductor on insulating dielectric: SeOI) substrate by the biasing of a back control gate arranged in the base substrate, under the insulating layer, facing the channel of the transistor.

In this Figure 6, the central curve C_n represents an example of the nominal characteristic $\log(I_D(V_G))$ (transistor without back control gate).

The following values are only examples. It is clear that the values of I_{ON} can vary according to the technology between $100 \mu A/\mu m$ et $2000 \mu A/\mu m$, the current I_{OFF} possibly varying between $1 fA/\mu m$ et $30 nA/\mu m$.

The currents I_{ON} and I_{OFF} are respectively established at $150 \mu A/\mu m$ and $5 nA/\mu m$.

The bottom curve C_{VT-} represents the nominal characteristic $\log(I_D(V_G))$ under the effect of a back control gate with working function and controlled at 0 V. This bottom curve illustrates the increase in the threshold voltage. The currents I_{ON} and I_{OFF} are respectively established at $100 \mu A/\mu m$ and $200 pA/\mu m$.

The top curve C_{VT+} represents the nominal characteristic $\log(I_D(V_G))$ under the effect of a back control gate without working function and controlled with a nominal power supply voltage V_{DD} . This top curve illustrates the reduction in the threshold voltage. The currents I_{ON} and I_{OFF} are established respectively at $200 \mu A/\mu m$ and $100 nA/\mu m$.

It will thus be understood that, by biasing the back control gate positively or negatively, all the space between the bottom C_{VT-} and top C_{VT+} curves can be covered, by thus modulating the threshold voltage of the transistor and its characteristic currents I_{ON} and I_{OFF} .

The invention allows a reduction/increase in the apparent width of the channel that becomes all the greater as the power supply voltages become lower, which is reflected in a substantial variation in I_{ON} and I_{OFF} .

It will be noted in this respect that the trend in the technical field of the invention is to utilize, for the future generations, electronic components with lower and lower power supply voltages. The invention is thus a priori of even more interest for the future generations.

There now follows a detailed description of the method of controlling the memory cell in the three operating modes: standby, write and read.

Standby mode

As shown in the table below, in the standby mode, the access transistors T1 and T4 are blocked, which causes the inverters of the bit lines BL1 and BL2 to be disconnected.

The power supply voltage V_{DD} is applied to the base substrate 2 and to the well 5 containing the back control gate BG2, while a zero voltage is applied to the well 4 containing the back control gate BG1.

5 A voltage that is low compared to V_{DD} , V_{BG1} is applied to the back control gate BG1 of the access transistors T1 and T4.

The threshold voltage of the transistors T1 and T4 is therefore increased, and all the more so if the BG voltage is low.

The result of this is that the conduction current I_{ON} and the leakage current I_{OFF} are minimized (represented by the - sign in the table below).

10 V_{BG2} denotes the voltage applied to the back control gate BG2 of the transistors T2, T3, T5 and T6.

In the standby mode, the voltage V_{BG2} is reduced.

For the NFET transistors T2 and T5, the leakage current is reduced accordingly.

15 For the PFET transistors T3 and T6, the leakage current may be higher; however, in an SRAM cell, PFET transistors of low conductivity and little leakage are generally used.

Transistor	T1	T2	T3	T4	T5	T6
State	OFF	ON	OFF	OFF	OFF	ON
V_{BG2}		0 V	0 V		0 V	0 V
V_{BG1}	0 V			0 V		
I_{ON}	-	+	=	-	+	=
I_{OFF}	-	-	=	-	-	=

The leaks within the memory cell and originating from the bit lines are therefore minimized.

Write mode

20 In the write mode, a high power supply voltage is applied to the well 4 containing the back control gate BG1; the well 5 containing the back control gate BG2 remains connected to ground GND.

A low voltage V_{BG2} is maintained for the back control gate of the transistors T2, T3, T5 and T6 forming the inverters.

25 The NFET transistors T2 and T5 therefore remain weak, like the PFET transistors T3 and T6 which are weak by their construction.

The voltage of the well 4 is transmitted to the back control gate BG1 of the access transistors T1 and T4.

This causes the threshold voltage of said transistors to be reduced and therefore causes them to be "boosted" (higher current I_{ON}).

The conditions applied to the (powerful) access transistors on the one hand, and weak inverters on the other, make it possible to pass easily from the bit lines to the memory cell, and therefore to proceed with a write.

Transistor	T1	T2	T3	T4	T5	T6
State	ON	ON	OFF	ON	OFF	ON
V_{BG2}		0 V	0 V		0 V	0 V
V_{BG1}	High			High		
I_{ON}	+	-	++	+	-	++
I_{OFF}	+	-	=	+	-	=

5 Read mode

In read mode, a low power supply voltage is applied to the well 4 containing the back control gate BG1, which is transmitted to BG1. The base substrate under the well 4 is still kept connected to GND. The well 5 containing the back control gate BG2 remains grounded.

10 A high positive voltage V_{BG2} (for example of the order of VDD) is applied to the back control gate BG2 of the transistors T2, T3, T5 and T6 forming the inverters.

The NFET transistors T2 and T5 become strong, and the apparent width of their channel is increased, while the PFET transistors T3 and T6 are weak by their construction.

Regarding the access transistors T1 and T4, the voltage V_{BG1} applied to the back control gate is low.

15 The conditions applied to the (weak) access transistors on the one hand, and powerful inverters on the other, make it possible to protect the content of the cell from any disturbances by the BL voltages, while providing a read signal that is sufficient for detection by a peripheral amplifier.

Transistor	T1	T2	T3	T4	T5	T6
State	ON	ON	OFF	ON	OFF	ON
V_{BG2}		High	High		High	High
V_{BG1}	0 V			0 V		
I_{ON}	-	+	=	-	+	=
I_{OFF}	-	++	=	-	++	=

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The advantages of the invention are as follows.

The use of an FD-SOI type substrate associated with a back gate for each transistor makes it possible to modulate the apparent size of the transistors, in order to obtain secured reading, easy writing and a standby mode with leaks minimized.

Moreover, the FD-SOI substrate can be used to form non-doped channel transistors
5 thus eliminating the variability brought about by the random distribution of the doping. This makes it possible to use transistors of minimal size without compromising the stability of the memory cell.

The present invention adapts the ratios to the operating mode and therefore improves the margins in each of the modes without compromising the correct operation of the other
10 modes.

Also, the action is done in rows (parallel to the word line WL, all the cells activated on this WL) and therefore does not disturb the other cells of the column.

All these provisions make it possible to further reduce the dimensions of the transistors and therefore of the cell.

15 It goes without saying that the examples that have just been given are purely particular illustrations and do not in any way limit the fields of application of the invention.

Thus, the memory cell can also operate in a so-called "sub-threshold" mode (or "sub-threshold conduction mode") in which the power supply voltage VDD is less than the threshold voltages.

20 This type of cell is of particular benefit in very low power applications.

The SRAM cell according to the present invention operates with power supply voltages VDD that are lower than for the existing "sub-threshold" cells, in as much as it makes it possible to reduce the threshold voltages and the voltage VDD is lower.

The leakage currents are then reduced accordingly and more effectively than in existing
25 cells.

CLAIMS

1. SRAM-type memory cell comprising:

- a semiconductor on insulator substrate comprising a thin film of semiconductor material separated from a base substrate by an insulating layer;
- six transistors, comprising two access transistors, two conduction transistors and two charge transistors arranged so as to form with said conduction transistors two back-coupled inverters, each of the transistors comprising a drain region and a source region arranged in the thin film, a channel extending between the source region and the drain region and a front gate situated above the channel,

said memory cell being **characterized** in that each of the transistors has a back control gate formed in the base substrate below the channel and able to be biased in order to modulate the threshold voltage of the transistor, a first back gate line connecting the back control gates of the access transistors to a first potential and a second back gate line connecting the back control gates of the conduction transistors and charge transistors to a second potential, the first and second potentials being modulated according to the type of cell control operation.

2. Memory cell according to Claim 1, characterized in that the access transistors and conduction transistors are NFET transistors, the charge transistors are PFET transistors, and in that the back control gate of the access transistors is of N+ conductivity and the back control gate of the conduction transistors and charge transistors is of P+ conductivity.

3. Memory cell according to either of Claims 1 and 2, characterized in that the back control gate of the conduction transistors and charge transistors is arranged in the base substrate below the channel in a well of conductivity opposite to the conductivity of the back control gate.

4. Memory cell according to one of Claims 1 to 3, characterized in that it is fully depleted.

5. Memory array comprising a plurality of SRAM cells according to one of Claims 1 to 4, **characterized** in that the channel of each of the transistors has a minimal physical

width but has an apparent width that can be modulated by the application of a potential to the back control gate of said transistor.

6. Method of fabricating an SRAM-type memory cell according to Claim 1, **characterized** in that it comprises the steps of:

- providing said semiconductor on insulator substrate comprising said thin film of semiconductor material separated from the base substrate by said insulating layer,
- forming back control gates in the base substrate by implantation.

7. Method of controlling a memory cell according to one of Claims 1 to 4, **characterized** in that a so-called “high” positive voltage and a so-called “low” positive or zero voltage less than the high voltage is defined to bias the back control gates of the transistors, and in that, according to the type of cell control operation, a high voltage or a low voltage is dynamically applied to the back control gate of the transistors.

8. Method according to Claim 7, characterized in that it comprises, for a standby operation, the application of a low voltage to the back control gate of the access transistors and to the back control gate of the conduction transistors and charge transistors.

9. Method according to either of Claims 7 and 8, characterized in that it comprises, for a read operation, the application of a low voltage to the back control gate of the access transistors and a high voltage to the back control gate of the conduction transistors and charge transistors.

10. Method according to one of Claims 7 to 9, characterized in that it comprises, for a write operation, the application of a high voltage to the back control gate of the access transistors and a low voltage to the back control gate of the conduction transistors and charge transistors.